

描述 / Descriptions

SOT-23 塑封封装 硅半导体二极管。Silicon Diode in a SOT-23 Plastic Package.

特征 / Features

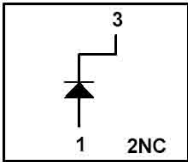
小信号二极管。无卤产品。

Small signal diode.HF Product.

用途 / Applications

高导电率的超快速二极管。

High Conductance Ultra Fast Diode.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN: See Equivalent Circuit.

放大及印章代码 / h_{FE} Classifications & Marking

| | |
|---------|-----|
| Marking | HA6 |
|---------|-----|

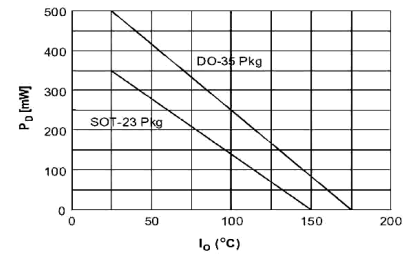
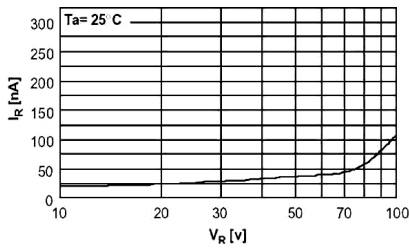
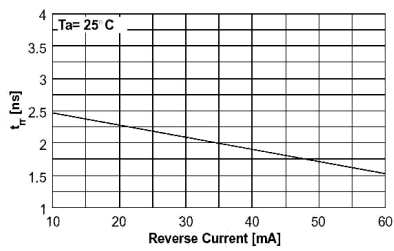
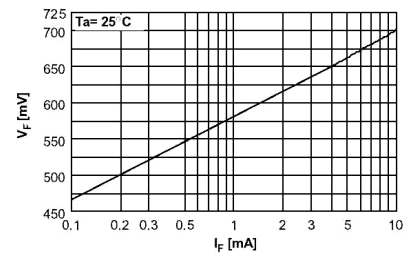
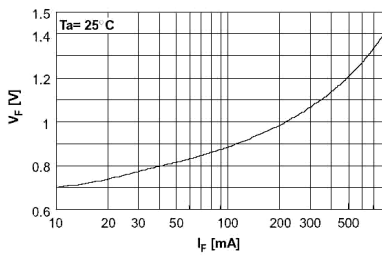
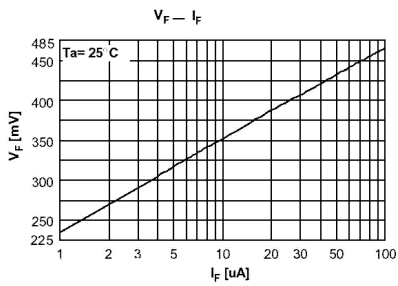
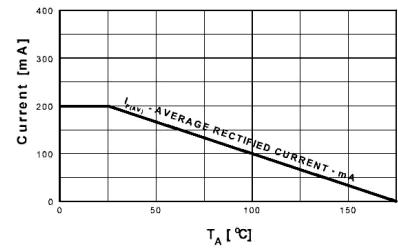
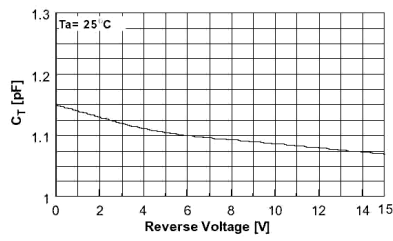
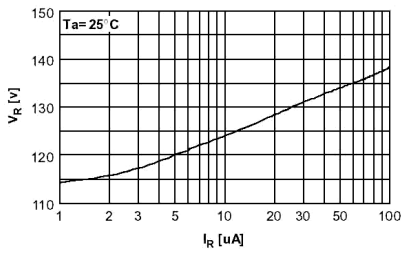
极限参数 / Absolute Maximum Ratings(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 数值 Rating | 单位 Unit |
|---|----------------------|--------------|------------|
| Maximum Repetitive Reverse Voltage | V_{RRM} | 85 | V |
| Average Rectified Forward Current | $I_{F(AV)}$ | 200 | mA |
| Non-repetitive Peak Forward Surge Current | $I_{FSM(1)}(PW=1S)$ | 1.0 | A |
| | $I_{FSM(2)}(PW=1mS)$ | 2.0 | A |
| Power Dissipation | P_D | 350 | mW |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 357 | °C/W |
| Junction Temperature | T_J | 150 | °C |
| Storage Temperature Range | T_{stg} | -55~150 | °C |

电性能参数 / Electrical Characteristics(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 测试条件 Test Conditions | 最小值 Min | 典型值 Typ | 最大值 Max | 单位 Unit |
|-------------------------------|--------------|--|------------|------------|------------|------------|
| Breakdown Voltage | V_R | $I_R=5.0\mu A$ | 85 | | | V |
| Forward Voltage | V_F | $I_F=1.0mA$ | | | 715 | mV |
| | | $I_F=10mA$ | | | 855 | mV |
| | | $I_F=50mA$ | | | 1.0 | V |
| | | $I_F=150mA$ | | | 1.25 | V |
| Instantaneous Reverse Current | I_R | $V_R=75V$ | | | 1.0 | μA |
| | | $V_R=25V$ $T_A=150^\circ C$ | | | 30 | μA |
| | | $V_R=75V$ $T_A=150^\circ C$ | | | 50 | μA |
| Total Capacitance | C_T | $V_R=0$ $f=1.0MHz$ | | | 2.0 | pF |
| Reverse Recovery Time | t_{rr} | $I_F=I_R=10mA$ $I_{RR}=1.0mA$ $R_L=100\Omega$ | | | 6.0 | ns |

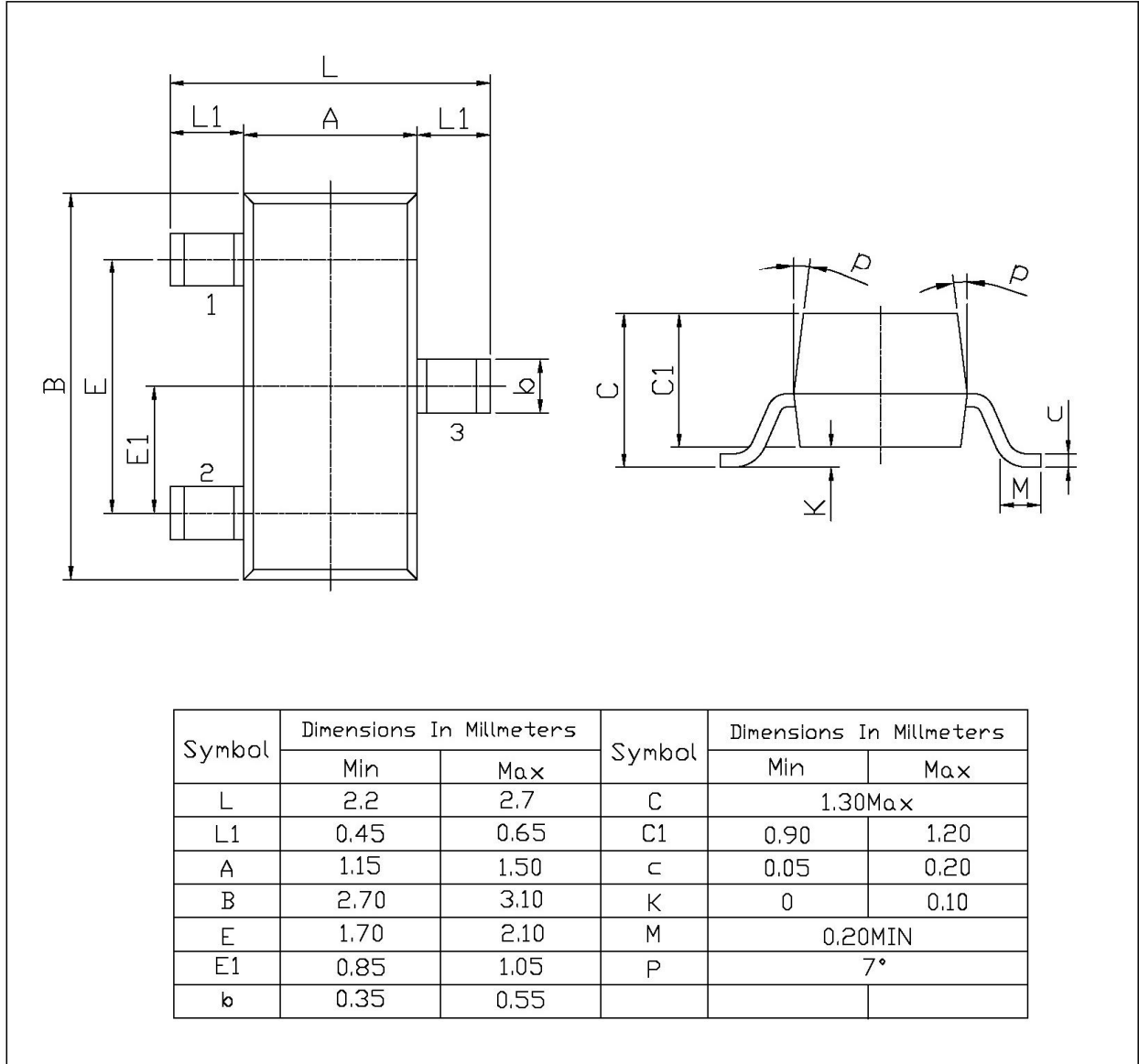
电参数曲线图 / Electrical Characteristic Curve



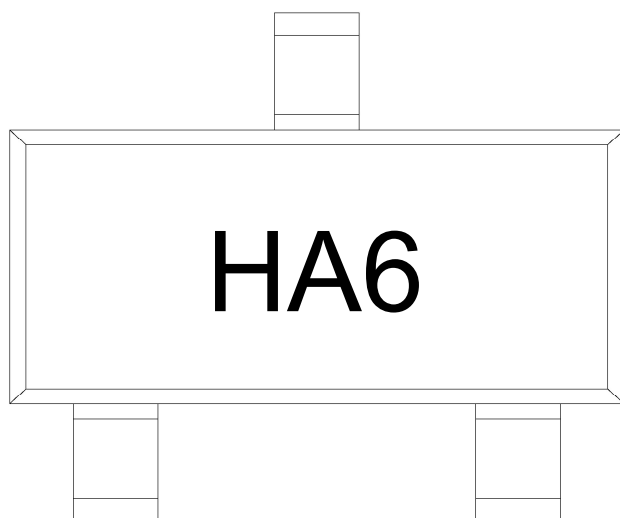
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

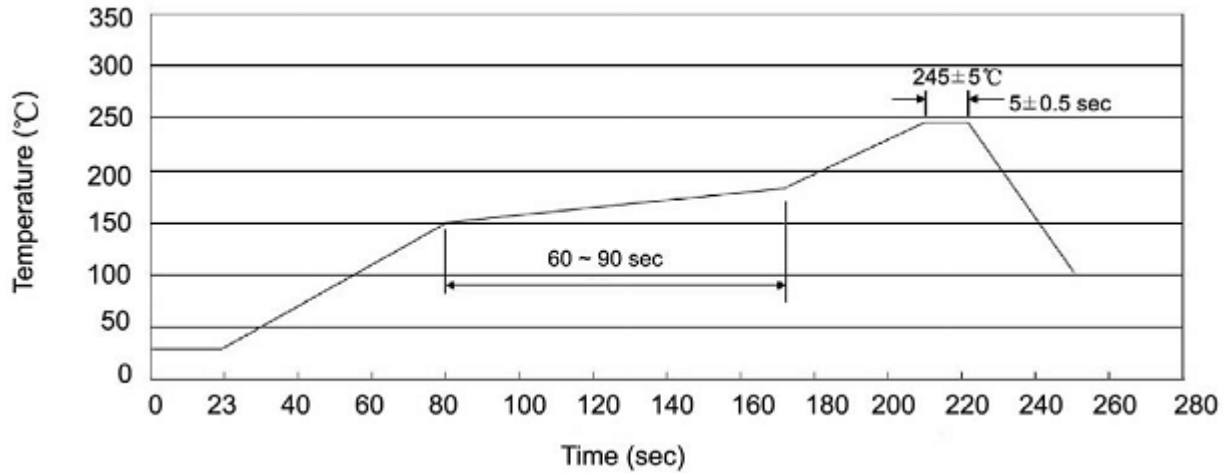
A6： 为型号代码

Note:

H: Company Code.

A6: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: mm ³) | | |
|----------------------|--------------------|-------------------------|------------------------|------------------------------|------------------------|---|-------------|-------------|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box 盒 | Outer Box 箱 |
| SOT-23 | 3,000 | 10 | 30,000 | 8 | 240,000 | 7" ×8 | 180×120×180 | 385×257×392 |

使用说明 / Notices